CLAIMS

1. An electronic member fabricating method comprising:

an adhesive material attaching process for attaching a wafer to a thermosetting adhesive material provided on a base film;

a dicing-film attaching process for attaching the base film to a dicing film;

an IC-chip separating process for cutting the wafer and the thermosetting adhesive material to divide them into IC chips; and

a mounting process for attaching, to a carrier, the IC chips having the thermosetting adhesive material attached thereto;

wherein the thermosetting adhesive material has a viscosity of 20000 Pa·s or less at the attaching temperature during the adhesive material attaching process.

2. An electronic member fabricating method comprising:

an adhesive material attaching process for attaching a thermosetting adhesive material at least to a wafer;

a dicing-film attaching process for attaching a dicing film to the thermosetting adhesive material;

an IC-chip separating process for cutting the wafer and the thermosetting adhesive material to divide them into IC chips; and

a mounting process for attaching, to a carrier, the IC chips having the thermosetting adhesive material attached thereto;

wherein the thermosetting adhesive material has a viscosity of 20000 Pa·s or less at the attaching temperature during the adhesive material attaching process.

3. The electronic member fabricating method according to

Claim 2, wherein the thermosetting adhesive material is covered with a base film in advance.

4. The electronic member fabricating method according to Claim 3, wherein the dicing-film attaching process includes a process for peeling the base film and a process for attaching the dicing film to the thermosetting adhesive material.

5. An electronic member fabricating method comprising:

an adhesive material attaching process for attaching, at least to a wafer, a base film including a thermosetting adhesive material adhered thereon;

a cutting process for cutting the wafer and the thermosetting adhesive material to divide them into IC chips by using the base film as a dicing film; and

a mounting process for attaching, to a carrier, the IC chips having the thermosetting adhesive material attached thereto;

wherein the thermosetting adhesive material has a viscosity of 20000 Pa·s or less at the attaching temperature during the adhesive material attaching process.

6. The electronic member fabricating method according to Claims 1 to 5, wherein the thermosetting adhesive material has a viscosity of 100 Pa·s or more at the attaching temperature during the adhesive material attaching process.

7. The electronic member fabricating method according to any of Claims 1 to 6, wherein the thermosetting adhesive material does not start the heat curing reaction at the attaching temperature during the adhesive material attaching process.

8. The electronic member fabricating method according to Claims 1 to 6, wherein the attaching temperature during the adhesive material attaching process is lower than the temperature that starts heat curing of the thermosetting adhesive material.

9. The electronic member fabricating method according to Claims 1 to 8, wherein the thermosetting adhesive material has a viscosity of 20000 Pa·s or less at the attaching temperature during the mounting process.

10. The electronic member fabricating method according to Claim 9, wherein the thermosetting adhesive material has a viscosity of 100 Pa·s or more at the attaching temperature during the mounting process.

11. The electronic member fabricating method according to any of Claims 1 to 10, wherein the thermosetting adhesive material does not start the heat curing reaction at the attaching temperature during the mounting process.

12. The electronic member fabricating method according to Claims 1 to 11, further comprises a process for heating the thermosetting adhesive material to cause the heat curing reaction, after the mounting process.

13. The electronic member fabricating method according to Claims 1 to 12, wherein the thermosetting adhesive material is of a film type or a paste type.

14. The electronic member fabricating method according to Claims 1 to 13, wherein a dicing saw is used in the cutting process.

15. An adhesive-applied IC chip including an IC chip and an

adhesive material adhered to the back surface of the IC chip, wherein the adhesive material is directly attached on a base film or a dicing film, the adhesive material contains at least a thermosetting resin, the adhesive material has not started the curing reaction and the adhesive material has a viscosity of 20000 Pa·s or less at temperatures equal to or less than the curing-reaction starting temperature.

16. The electronic member fabricating method according to Claim 15, wherein the adhesive material has a viscosity of 100 Pa·s or more at temperatures equal to or less than the curing-reaction starting temperature.

17. The adhesive-applied IC chip according to Claims 15 to 16, wherein the adhesive material starts the curing reaction at a temperature in the range of 80 to 120°C.

18. The adhesive-applied IC chip according to Claims 15 to 17, wherein the adhesive material is a film-type resin.

19. The adhesive-applied IC chip according to Claims 15 to 18, wherein the IC chip has a thickness of 200 micrometers or less.

20. The adhesive-applied IC chip according to Claims 15 to 19, wherein the adhesive material has substantially the same size as that of the IC chip.